Semiconductor Device Type: (DMA) 008 MSOP 3x3x1 NiPdAu

Termination Base Alloy: Copper Alloy (Cu)

Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)

J-STD-609A Product Marking and/or Pkg. Labeling e4

Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm
Silica, vitreous	60676-86-0	Mold Compound	45.305	11.372	453,050
Epoxy Resin	Trade Secret	Mold Compound	3.265	0.819	32,646
Phenolic Resin	Trade Secret	Mold Compound	3.265	0.819	32,646
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.306	0.328	13,059
Carbon Black	1333-86-4	Mold Compound	0.160	0.040	1,599
Copper	7440-50-8	Lead Frame	39.490	9.912	394,901
Nickel	7440-02-0	Lead Frame	1.232	0.309	12,315
Silicon	7440-21-3	Lead Frame	0.267	0.067	2,668
Magnesium	7439-95-4	Lead Frame	0.062	0.015	616
Silver (Ag)	7440-22-4	Die Attach	0.895	0.225	8,949
Proprietary Resin	Trade Secret	Die Attach	0.211	0.053	2,109
Proprietary Curing agent & Hardener	Trade Secret	Die Attach	0.034	0.009	342
Silicon	7440-21-3	Chip (Die)	2.250	0.565	22,500
Gold	7440-57-5	Wire Bond	0.420	0.105	4,200
Nickel	7440-02-0	Plating on external leads (pins)	1.697	0.426	16,970
Palladium	7440-05-3	Plating on external leads (pins)	0.137	0.034	1,374
Gold	7440-57-5	Plating on external leads (pins)	0.006	0.001	55
		TOTALS:	100.000	25.100	1,000,000

0.0251 g Total Mass

13.38	(mg) Total	Mold Compound	% ot Total Weight	53.30
	Silica, vitreous	60676-86-0	85.00	
	Epoxy Resin	Trade Secret	6.13	
	Phenolic Resin	Trade Secret	6.13	
	Epoxy, Cresol Novolac	29690-82-2	2.45	
	Carbon Black	1333-86-4	0.30	
		Total	100.00	

10.30	(mg) Total	Lead Frame	% of Total Weight	41.05
	Copper	7440-50-8	96.20	
	Nickel	7440-02-0	3.00	
	Silicon	7440-21-3	0.65	
	Magnesium	7439-95-4	0.15	
		Total	100.00	

0.29	(mg) Total	Die Attach	% of Total Weight	1.14
	Silver (Ag)	7440-22-4	78.50	
	Proprietary Resin	Trade Secret	18.50	
	Proprietary Curing agent & Hard	Trade Secret	3.00	
		Total	100.00	

0.56	Total (mg)	Chip (Die)	% of Total Weight	2.25
	Doped Silicon	7440-21-3	100.00	
		Total	100.00	

0.11	(mg) Total	Wire Bond	% of Total Weight	0.42
	Gold	7440-57-5	100.00	
		Total	100.00	

0.46	(mg) Total	Plating on external leads (pins)	% of Total Weight	1.84
	Nickel	7440-02-0	92.23	
	Palladium	7440-05-3	7.47	
	Gold	7440-57-5	0.30	
		Total	100.00	

25.10 100.00

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table